

DESCRIPTION

~~WORKPIECE CUTTING METHOD AND WORKPIECE HOLDING TOOL~~

TECHNICAL FIELD

[0001]

The present invention relates to a method for slicing a workpiece with a wire saw and to a workpiece holder used in the method.

BACKGROUND ART

[0002]

When a workpiece is sliced into wafers with a wire saw, slicing is performed so that the sliced plane has a predetermined orientation. The slicing method begins with measuring an axis orientation of the workpiece while holding and fixing the workpiece with a workpiece holder. On the basis of the data of the measured axis orientation, the workpiece holder is fixed to a wire saw, the workpiece position is adjusted, and the workpiece is then sliced such that the crystal axis orientation of the workpiece coincides with a desired plane orientation of the wafer. The plane orientation of the sliced plane of the workpiece is adjusted by a combination of a rotating motion around an axis perpendicular to a central axis between the bottoms of the cylindrical workpiece in a plane parallel to the wire row and a swinging motion of the central axis between the bottoms relative to the wire row plane. Such a method for adjusting a crystal plane orientation of a workpiece is referred to as an internal setup manner.

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